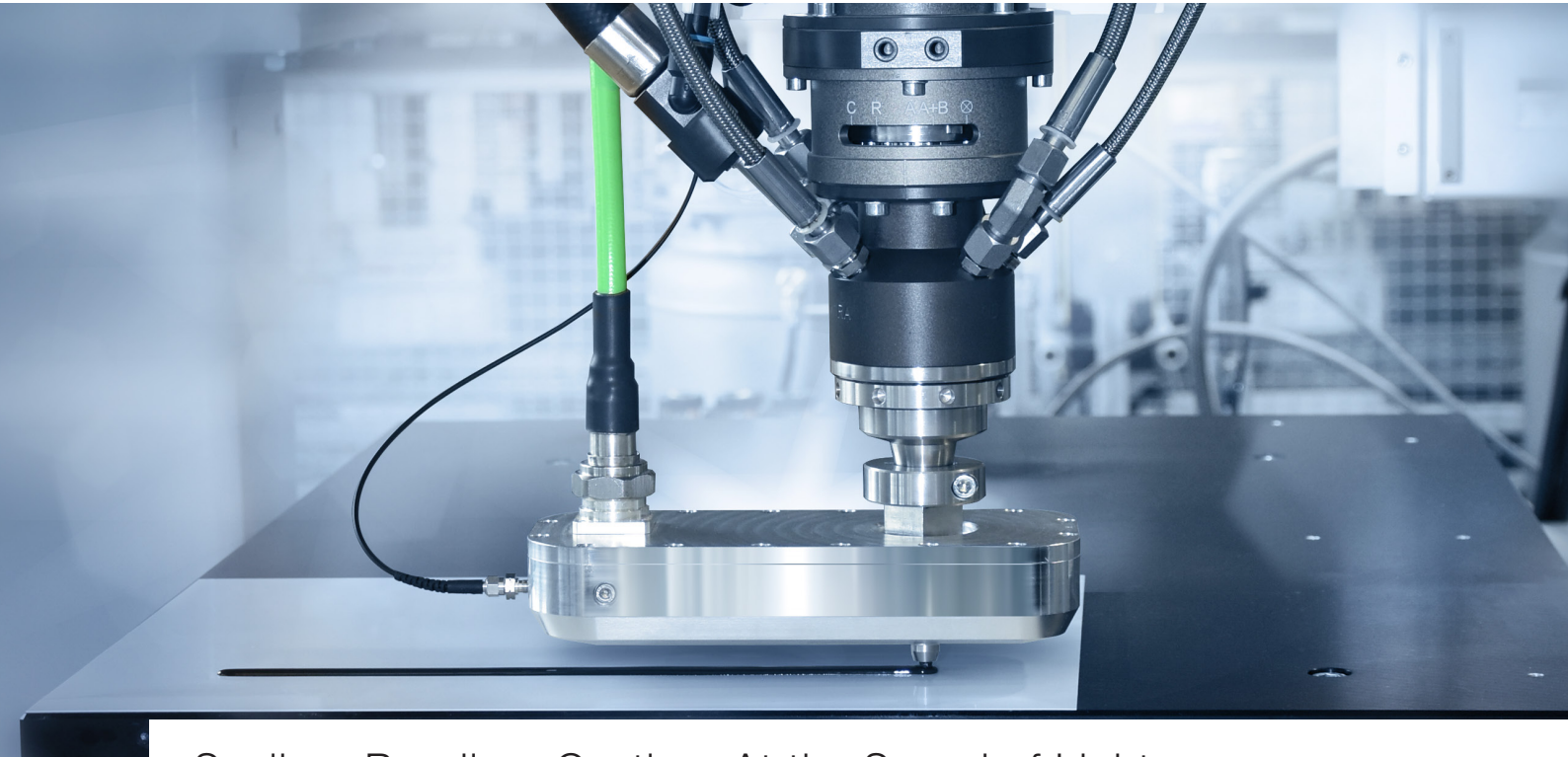


Next Generation Speed Technology

RAKU[®] MC Microwave Curing – faster than ever.



Sealing, Bonding. Casting. At the Speed of Light.

Patented* technology

With the microwave technology, RAMPF has developed the Next Generation Speed Technology for **sealing systems, adhesives, and casting resins**. Before it is applied to the component, the material is volumetrically activated by microwave radiation directly after the application nozzle and during the flow process.

* Pending



Faster handling of components

Due to microwave activation, the 2-component reactive resin reacts approx. 4 times faster. This allows the component to be loaded much faster or to be fed to a further processing step.



Higher machine availability

In a 2-component low pressure machine, the mixing and activation of the material takes place in one step. For the first time ever, our patented* RAKU[®] MC technology makes it possible to separate the mixing and activation process. This significantly reduces contamination in the mixing head. The number of rinsing processes is reduced, whilst and the service life of the mixing head and machine availability are increased.



Greater economic efficiency

Microwave technology activates the material, thereby significantly shortening the curing time. In case of an oven-curing-system, it may even be possible to dispense entirely without curing ovens. This results in lower energy consumption and equipment investment. Furthermore, the size of the plant is reduced.

RAMPF Polymer Solutions GmbH & Co. KG

Robert-Bosch-Straße 8–10 | 72661 Grafenberg | Germany
T +49.7123.9342-0 | E polymer.solutions@rampf-group.com
www.rampf-group.com

RAMPF Production Systems GmbH & Co. KG

Römerallee 14 | 78658 Zimmern o.R | Germany
T +49.741.2902-0 | E production.systems@rampf-group.com
www.rampf-group.com